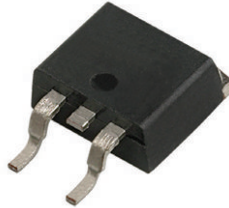
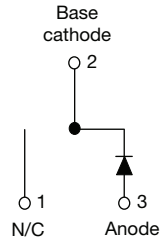


Ultralow V_F Hyperfast Rectifier for Discontinuous Mode PFC, 8 A, FRED Pt®


D²PAK (TO-263AB)

FEATURES

- Benchmark ultralow forward voltage drop
- Hyperfast recovery time
- Low leakage current
- 175 °C operating junction temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Meets JESD 201 class 1 whisker test
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
 COMPLIANT
 HALOGEN
FREE

| PRIMARY CHARACTERISTICS | |
|-------------------------|-------------------------------|
| $I_{F(AV)}$ | 8 A |
| V_R | 600 V |
| V_F at I_F | 0.81 V |
| t_{rr} typ. | 60 ns |
| T_J max. | 175 °C |
| Package | D ² PAK (TO-263AB) |
| Circuit configuration | Single |

DESCRIPTION

State of the art, ultralow V_F , soft-switching hyperfast rectifiers optimized for discontinuous (critical) mode (DCM) power factor correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

APPLICATIONS

AC/DC SMPS 70 W to 400 W

e.g. laptop and printer AC adaptors, desktop PC, TV and monitor, games units and DVD AC/DC power supplies.

| ABSOLUTE MAXIMUM RATINGS | | | | |
|---------------------------------------------|----------------|-----------------|-------------|-------|
| PARAMETER | SYMBOL | TEST CONDITIONS | MAX. | UNITS |
| Peak repetitive reverse voltage | V_{RRM} | | 600 | V |
| Average rectified forward current | $I_{F(AV)}$ | $T_C = 160$ °C | 8 | A |
| Non-repetitive peak surge current | I_{FSM} | $T_J = 25$ °C | 175 | |
| Peak repetitive forward current | I_{FM} | | 16 | |
| Operating junction and storage temperatures | T_J, T_{Stg} | | -55 to +175 | °C |

| ELECTRICAL SPECIFICATIONS ($T_J = 25$ °C unless otherwise specified) | | | | | | |
|-----------------------------------------------------------------------|---------------|--------------------------------------------------------|------|--------------|--------------|---------|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS |
| Breakdown voltage, blocking voltage | V_{BR}, V_R | $I_R = 100$ μ A | 600 | - | - | V |
| Forward voltage | V_F | $I_F = 8$ A $I_F = 8$ A, $T_J = 150$ °C | - | 0.96 0.81 | 1.05 0.86 | |
| Reverse leakage current | I_R | $V_R = V_R$ rated $T_J = 150$ °C, $V_R = V_R$ rated | - | 0.05 20 | 5 100 | μ A |
| Junction capacitance | C_T | $V_R = 600$ V | - | 17 | - | pF |
| Series inductance | L_S | Measured lead to lead 5 mm from package body | - | 8.0 | - | nH |



| DYNAMIC RECOVERY CHARACTERISTICS ($T_C = 25\text{ }^\circ\text{C}$ unless otherwise specified) | | | | | | | |
|-------------------------------------------------------------------------------------------------|-----------|------------------------------------------------------------------------------------|-----------------------------------|------|------|-------|---------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS | |
| Reverse recovery time | t_{rr} | $I_F = 1\text{ A}$, $di_F/dt = 100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$ | - | 60 | 100 | ns | |
| | | $I_F = 8\text{ A}$, $di_F/dt = 100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$ | - | 150 | 250 | | |
| | | $T_J = 25\text{ }^\circ\text{C}$ | - | 170 | - | | |
| | | $T_J = 125\text{ }^\circ\text{C}$ | - | 250 | - | | |
| Peak recovery current | I_{RRM} | $I_F = 8\text{ A}$ $di_F/dt = 200\text{ A}/\mu\text{s}$ $V_R = 390\text{ V}$ | $T_J = 25\text{ }^\circ\text{C}$ | - | 15 | - | A |
| | | | $T_J = 125\text{ }^\circ\text{C}$ | - | 20 | - | |
| Reverse recovery charge | Q_{rr} | | $T_J = 25\text{ }^\circ\text{C}$ | - | 1.3 | - | μC |
| | | | $T_J = 125\text{ }^\circ\text{C}$ | - | 2.6 | - | |

| THERMAL - MECHANICAL SPECIFICATIONS | | | | | | |
|-------------------------------------------------|----------------|--------------------------------------------|--------------|------|------------|---------------------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS |
| Maximum junction and storage temperature range | T_J, T_{Stg} | | -65 | - | 175 | $^\circ\text{C}$ |
| Thermal resistance, junction to case per leg | R_{thJC} | | - | 1.4 | 2 | $^\circ\text{C}/\text{W}$ |
| Thermal resistance, junction to ambient per leg | R_{thJA} | Typical socket mount | - | - | 70 | |
| Thermal resistance, case to heatsink | R_{thCS} | Mounting surface, flat, smooth and greased | - | 0.5 | - | |
| Weight | | | - | 2.0 | - | g |
| | | | - | 0.07 | - | oz. |
| Mounting torque | | | 6.0 (5.0) | - | 12 (10) | kgf · cm (lbf · in) |
| Marking device | | Case style D ² PAK (TO-263AB) | 8ETL06SH | | | |

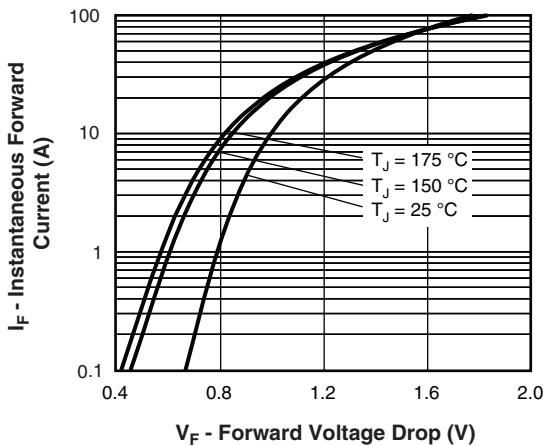


Fig. 1 - Typical Forward Voltage Drop Characteristics

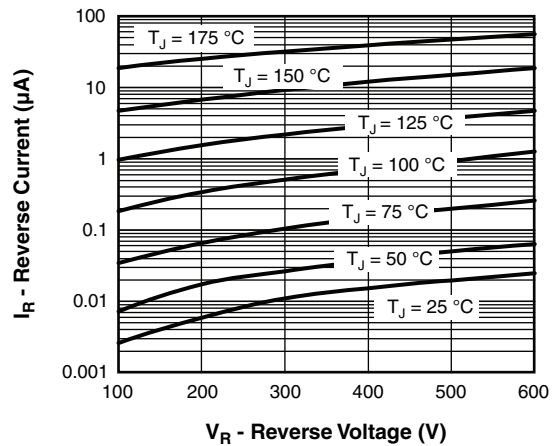


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

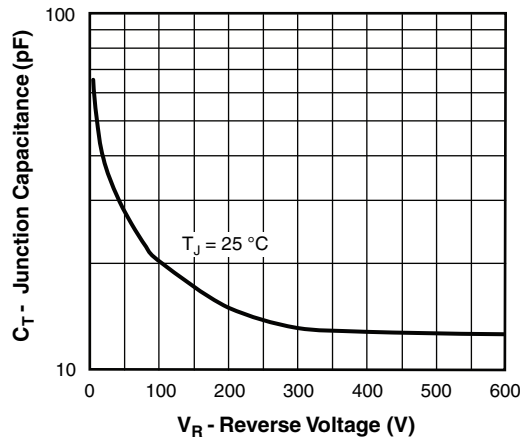


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

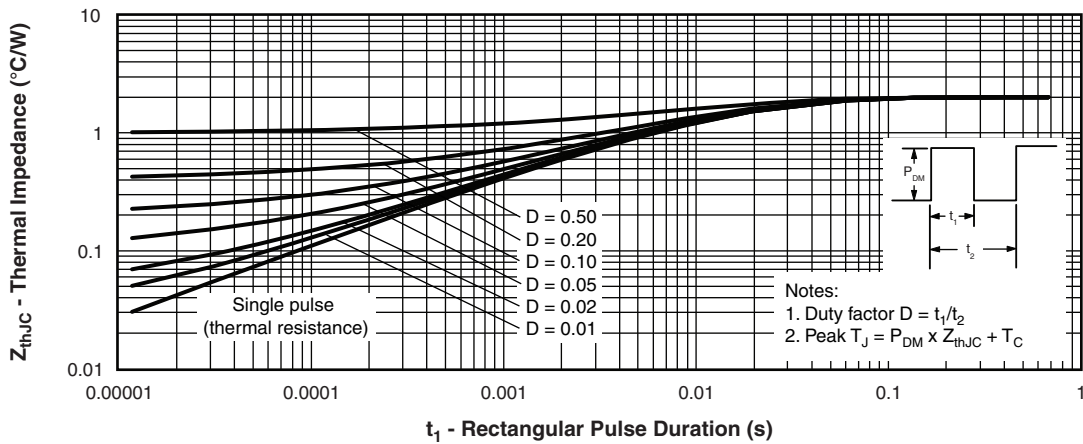


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

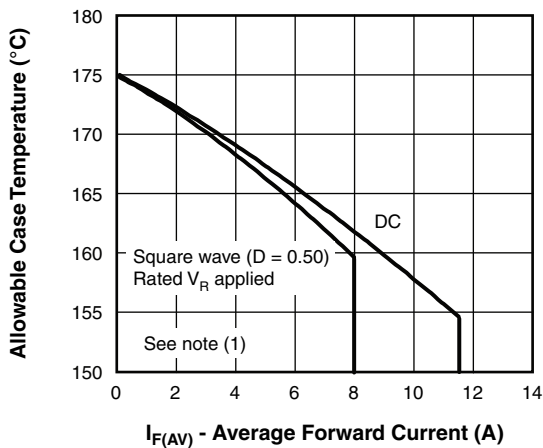


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

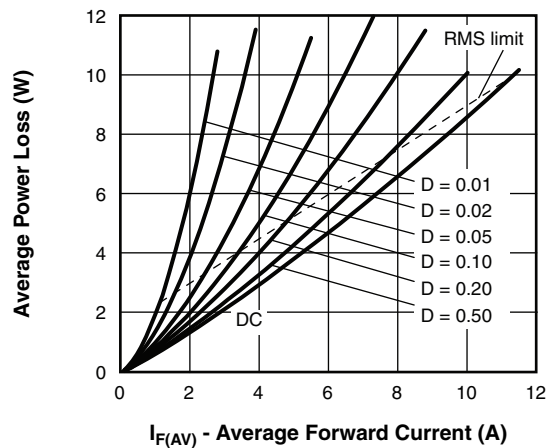


Fig. 6 - Forward Power Loss Characteristics

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
- P_d = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
- P_{dREV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R

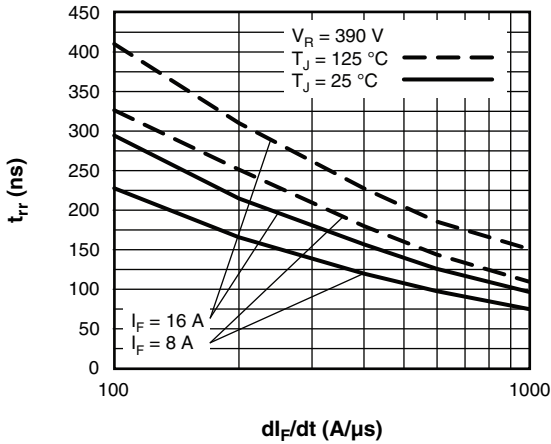


Fig. 7 - Typical Reverse Recovery Time vs. di_F/dt

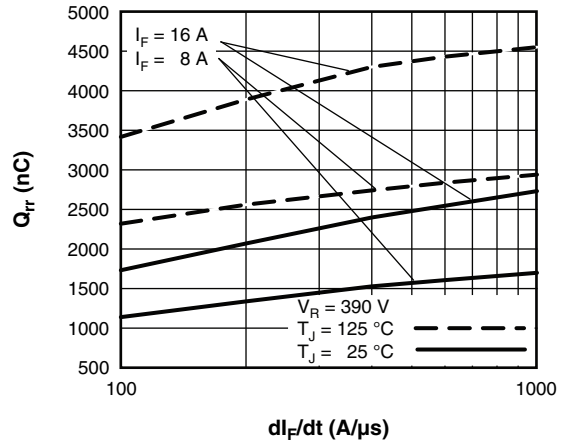


Fig. 8 - Typical Stored Charge vs. di_F/dt

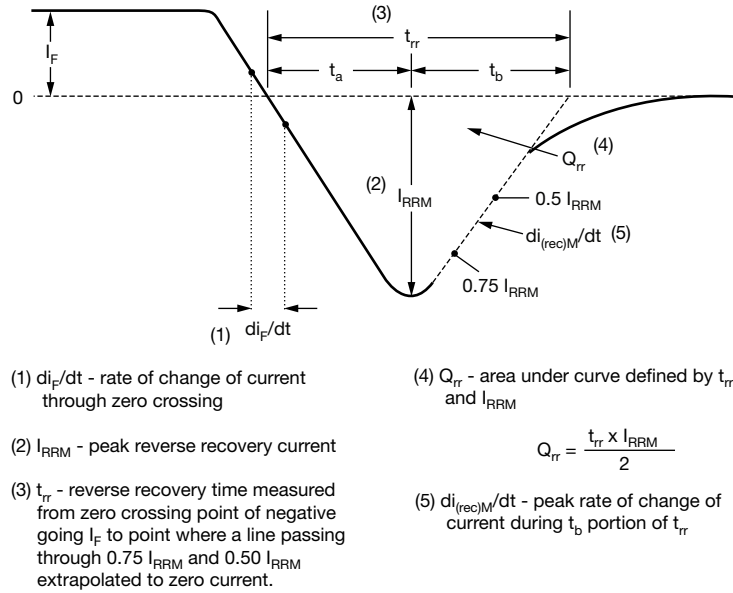
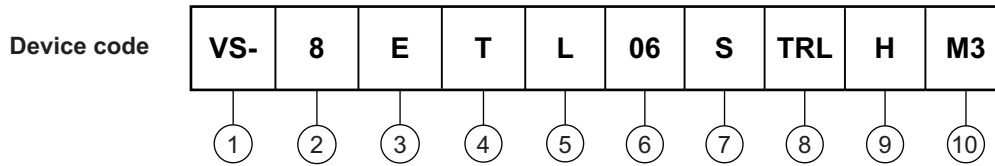


Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Current rating (8 A)
- 3** - E = single diode
- 4** - T = TO-220, D²PAK
- 5** - L = ultralow V_F hyperfast recovery
- 6** - Voltage rating (06 = 600 V)
- 7** - • S = D²PAK
- 8** - • None = tube (50 pieces)
• TRL = tape and reel (left oriented, for D²PAK package)
• TRR = tape and reel (right oriented, for D²PAK package)
- 9** - H = lead (Pb)-free
- 10** - M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

| ORDERING INFORMATION | | |
|-----------------------------|----------------------|------------------------------|
| PREFERRED P/N | BASE QUANTITY | PACKAGING DESCRIPTION |
| VS-8ETL06SHM3 | 50 | Antistatic plastic tube |
| VS-8ETL06STRRHM3 | 800 | 13" diameter reel |
| VS-8ETL06STRLHM3 | 800 | 13" diameter reel |

| LINKS TO RELATED DOCUMENTS | |
|-----------------------------------|------------------------------------------------------------------------|
| Dimensions | www.vishay.com/doc?95046 |
| Part marking information | www.vishay.com/doc?95444 |
| Packaging information | www.vishay.com/doc?95032 |
| SPIICE model | www.vishay.com/doc?96055 |

D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



| SYMBOL | MILLIMETERS | | INCHES | | NOTES | SYMBOL | MILLIMETERS | | INCHES | | NOTES |
|--------|-------------|-------|--------|-------|-------|--------|-------------|-------|-----------|-------|-------|
| | MIN. | MAX. | MIN. | MAX. | | | MIN. | MAX. | MIN. | MAX. | |
| A | 4.06 | 4.83 | 0.160 | 0.190 | | D1 | 6.86 | 8.00 | 0.270 | 0.315 | 3 |
| A1 | 0.00 | 0.254 | 0.000 | 0.010 | | E | 9.65 | 10.67 | 0.380 | 0.420 | 2, 3 |
| b | 0.51 | 0.99 | 0.020 | 0.039 | | E1 | 7.90 | 8.80 | 0.311 | 0.346 | 3 |
| b1 | 0.51 | 0.89 | 0.020 | 0.035 | 4 | e | 2.54 BSC | | 0.100 BSC | | |
| b2 | 1.14 | 1.78 | 0.045 | 0.070 | | H | 14.61 | 15.88 | 0.575 | 0.625 | |
| b3 | 1.14 | 1.73 | 0.045 | 0.068 | 4 | L | 1.78 | 2.79 | 0.070 | 0.110 | |
| c | 0.38 | 0.74 | 0.015 | 0.029 | | L1 | - | 1.65 | - | 0.066 | 3 |
| c1 | 0.38 | 0.58 | 0.015 | 0.023 | 4 | L2 | 1.27 | 1.78 | 0.050 | 0.070 | |
| c2 | 1.14 | 1.65 | 0.045 | 0.065 | | L3 | 0.25 BSC | | 0.010 BSC | | |
| D | 8.51 | 9.65 | 0.335 | 0.380 | 2 | L4 | 4.78 | 5.28 | 0.188 | 0.208 | |

Notes

- Dimensioning and tolerancing per ASME Y14.5 M-1994
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- Thermal pad contour optional within dimension E, L1, D1 and E1
- Dimension b1 and c1 apply to base metal only
- Datum A and B to be determined at datum plane H
- Controlling dimension: inch
- Outline conforms to JEDEC® outline TO-263AB



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